ABSTRACT OF THE DISCLOSURE

A carrier, semiconductor device, and their mounting method which improve reliability such as heat cycle resistance of the semiconductor device mounted on a circuit board. A semiconductor device 1 comprises a carrier for semiconductor 3, and a concave portion is formed at an area of an external electrode 8 of the carrier for semiconductor 3. The external electrode 8 is disposed at the bottom of the concave portion. A solder paste 13 is supplied to the concave portion, the semiconductor device 1 is flipped, and the semiconductor device 1 is mounted on the circuit board 12. The semiconductor 1 mounted on the circuit board 12 is heated to the temperature above the melting point of the solder paste 13.

This Sheet Has Been Replaced

